查询TP3056B供应商

- Complete PCM Codec and Filtering
 Systems Include:
 - Transmit High-Pass and Low-Pass Filtering
 - Receive Low-Pass Filter With (sin x)/x Correction
 - Active RC Noise Filters
 - μ-Law and A-Law Compatible Coder and Decoder
 - Internal Precision Voltage Reference
 - Serial I/O Interface
 - Internal Autozero Circuitry

description

The TP3056B monolithic serial interface combined PCM codec and filter device is comprised of a single-chip PCM codec (pulse code-modulated encoder and decoder) and analog filters. This device provides all the functions required to interface a full-duplex (2-wire) voice telephone circuit with a TDM (time-division-multiplexed) system. Primary applications include:

- Line interface for digital transmission and switching of T1/E1 carrier, PABX, and central office telephone systems
- Subscriber line concentrators
- Digital-encryption systems
- Digital voice-band data-storage systems
- Digital signal processing

The TP3056B is designed to perform the transmit encoding (A/D conversion) and receive decoding (D/A conversion), and the appropriate filtering of analog signals in a PCM system. This device is intended to be used at the analog termination of a PCM line or trunk. It requires a master clock of 2.048 MHz, a transmit/receive data clock that is synchronous with the master clock (but can vary from 64 kHz to 2.048 MHz), and transmit and receive frame-sync pulses. The TP3056B contains patented circuitry to achieve low transmit channel idle noise and is not recommended for applications in which the composite signals on the transmit side are below –55 dBm0.

This device, available in 16-pin N PDIP (plastic dual-in-line package) and 16-pin DW SOIC (small outline IC) packages, is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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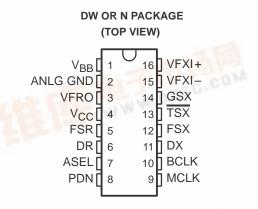
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

REDUCTION DATA information is current as of publication date. roducts conform to specifications per the terms of Texas Instruments tandard varianty. Production processing does not necessarily include esting of all parameters.

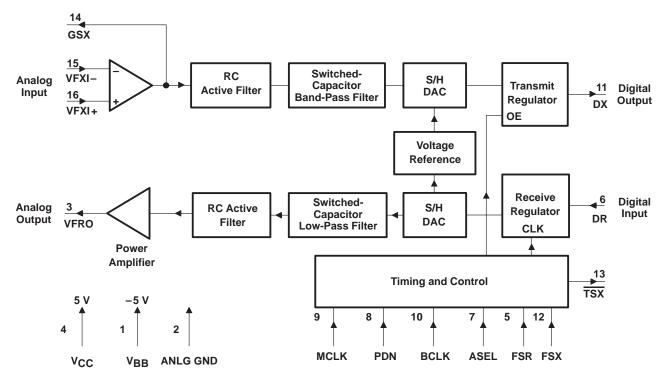


捷多邦,专业PCB打样工厂,24小时加急出货 TP3056B MONOLITHIC SERIAL INTERFACE COMBINED PCM CODEC AND FILTER SLWS072A – MAY 1998 – REVISED AUGUST 1998

- μ-Law/A-Law Operation Pin-Selectable
- ±5-V Operation
- Low Operating Power . . . 60 mW Typ
- Power-Down Mode ... 5 mW Typ _____
- Automatic Power Down
- TTL- or CMOS-Compatible Digital Interface
- Maximizes Line Interface Card Circuit
 Density



functional block diagram





Terminal Functions

	AL NO.	I/O	DESCRIPTION
ANLG GND	2		Analog ground. All signals are referenced to ANLG GND.
ASEL	7	I	A-law/ μ -law select. When ASEL is connected to V _{CC} , A-law is selected. When ASEL is connected to GND or V _{BB} , μ -law is selected.
BCLK	10	I	Transmit/receive bit clock. BCLK shifts PCM data out on DX during transmit and shifts PCM data in through DR during receive. BCLK can vary from 64 kHz to 2.048 MHz, but must be synchronous with MCLK.
DR	6	Ι	Receive data input. PCM data is shifted into DR at the trailing edge of the BCLK following the FSR leading edge.
DX	11	0	DX is the 3-state PCM data output that is enabled by FSX. Data is shifted out on the rising edge of BCLK.
FSR	5	I	Receive-frame sync pulse input. FSR enables BCLK to shift PCM data in DR. FSR is an 8-kHz pulse train (see Figures 1 and 2 for timing details).
FSX	12	I	Transmit-frame sync pulse. FSX enables BCLK to shift out the PCM data on DX. FSX is an 8-kHz pulse train (see Figures 1 and 2 for timing details).
GSX	14	0	Analog output of the transmit input amplifier. GSX is used to set gain externally.
MCLK	9	Ι	Transmit/receive master clock. MCLK must be 2.048 MHz.
PDN	8	I	Power down. When PDN is connected high, the device is powered down. When PDN is connected low or left floating, the device is powered up. PDN is internally tied low.
TSX	13	0	Transmit channel time-slot strobe. TSX is an open-drain output that pulses low during the encoder time slot.
V _{BB}	1		Negative power supply. $V_{BB} = -5 V \pm 5\%$
VCC	4		Positive power supply. V _{CC} = 5 V \pm 5%
VFRO	3	0	Analog output of the receive channel power amplifier
VFXI+	16	Ι	Noninverting input of the transmit input amplifier
VFXI-	15	Ι	Inverting input of the transmit input amplifier



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Supply voltage, V _{BB} (see Note 1)	
Voltage range at any analog input or output	V_{CC} +0.3 V to V _{BB} –0.3 V
Voltage range at any digital input or output	. V _{CC} +0.3 V to ANLG GND -0.3 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range: TP3056B	0°C to 70°C
Storage temperature range, T _{stg}	−65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to GND.

DISSIPATION RATING TABLE										
PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING						
DW	1025 mW	8.2 mW/°C	656 mW	533 mW						
N	1150 mW	9.2 mW/°C	736 mW	598 mW						

recommended operating conditions (see Note 2)

MIN	NOM	MAX	UNIT
4.75	5	5.25	V
-4.75	-5	-5.25	V
2.2			V
		0.6	V
		±2.5	V
10			kΩ
		50	pF
0		70	°C
	4.75 -4.75 2.2	4.75 5 -4.75 -5 2.2	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

[‡]Measured with CMRR > 60 dB

NOTE 2: To avoid possible damage to these CMOS devices and resulting reliability problems, the power-up procedure described in the device power-up sequence paragraphs later in this document should be followed.

electrical characteristics over recommended ranges of supply voltage operating free-air temperature range, in A-law and μ -law modes (unless otherwise noted)

supply current

	PARAMETER	TEST CONDITIONS	Г	UNIT				
PARAMETER		TEST CONDITIONS	MIN	TYP§	MAX	UNIT		
	Power down	No load		0.5	1	m A		
ICC	Supply current from V _{CC}	Operating	100 1000		6	9	mA	
		Power down	Power down	Nolood		0.5	1	~^^
IBB	Supply current from VBB	Operating	No load		6	9	mA	

§ All typical values are at V_{CC} = 5 V, V_{BB} = -5 V, and T_A = 25° C.



electrical characteristics at V_{CC} = 5 V $\pm 5\%,$ V_BB = –5 V $\pm 5\%,$ GND at 0 V, T_A = 25°C (unless otherwise noted)

digital interface

	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
VOH	High-level output voltage	DX	I _H = -3.2 mA	2.4		V
Vai	VOL Low-level output voltage	DX	I _L = 3.2 mA		0.4	V
VOL		TSX	I _L = 3.2 mA, Drain open		0.4	v
Чн	High-level input current		$V_{I} = V_{IH}$ to V_{CC}		±10	μΑ
Ι _{ΙL}	Low-level input current	All digital inputs	$V_I = GND$ to V_{IL}		±10	μΑ
Ioz	Output current in high-impedance state	DX	$V_{O} = GND$ to V_{CC}		±10	μΑ

analog interface with transmit amplifier input

	PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VICR [‡]	Common-mode input voltage range					±2.5	V
II.	Input current	VFXI+ or VFXI –	$V_{I} = -2.5 \text{ V} \text{ to } 2.5 \text{ V}$			±200	nA
r _i	Input resistance	VFXI+ or VFXI –	$V_{I} = -2.5 V$ to 2.5 V	10			MΩ
AV	Open-loop voltage amplification	VFXI+ to GSX		5000			
BI	Unity-gain bandwidth	GSX		1	2		MHz
VIO	Input offset voltage	VFXI+ or VFXI –				±20	mV
CMRR	Common-mode rejection ratio			60			dB
K _{SVR}	Supply-voltage rejection ratio			60			dB

[†] All typical values are at V_{CC} = 5 V, V_{BB} = -5 V, and T_A = 25° C. [‡] Measured with CMRR > 60 dB.

analog interface with receive amplifier output

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Receive output drive voltage		R _L = 10 kΩ			±2.5	V
Output resistance	VFRO			1	3	Ω
Load resistance		VFRO = ±2.5 V	600			Ω
Load capacitance	VFRO to GND				500	pF
Output dc offset voltage	VFRO to GND				±200	mV

[†] All typical values are at V_{CC} = 5 V, V_{BB} = -5 V, and T_A = 25° C.



operating characteristics, over operating free-air temperature range, V_{CC} = 5 V ±5%, V_{BB} = -5 V ±5%, GND at 0 V, V_I = 1.2276 V, f = 1.02 kHz, transmit input amplifier connected for unity gain, noninverting, in A-law and μ -law modes, (unless otherwise noted)

filter gains and tracking errors

PARAME	TER	TEST CONDI	TIONS	MIN	түр†	MAX	UNIT	
Maximum peak transmit	μ-law	3.17 dBm0			2.501		V	
overload level	A-law	3.14 dBm0			2.492		V	
Transmit filter gain, absolu	te‡ (at 0 dBm0)	$T_A = 25^{\circ}C$		- 0.15		0.15	dB	
		f = 16 Hz				-40		
		f = 50 Hz				-30		
		f = 60 Hz				-26		
		f = 200 Hz		-1.8		-0.1		
Transmit filter gain, relative	to obsolute [†]	f = 300 Hz to 3000 Hz		-0.15		0.15	dB	
Transmit litter gain, relative	e to absolute+	f = 3300 Hz		-0.35		0.05	uв	
		f = 3400 Hz		-0.8		0		
		f = 4000 Hz				-14		
		f ≥ 4600 Hz				22		
		(measure response from 0 Hz	: to 4000 Hz)			-32		
Absolute [‡] transmit gain va temperature and supply vo absolute transmit gain				-0.1		0.1	dB	
			$3 \text{ dBm0} \ge \text{input level}$ $\ge -40 \text{ dBm0}$	±0.2				
Transmit gain tracking error with level	Sinusoidal test method, Reference level = -10 dBm0	-40 dBm0 > input level ≥ -50 dBm0			±0.4	dB		
		−50 dBm0 > input level ≥ −55 dBm0			±0.8			
Receive filter gain, absolut	e [‡] (at 0 dBm0)	Input is digital code sequence T _A = 25°C	for 0-dBm0 signal,	-0.15		0.15	dB	
		f = 0 Hz to 3000 Hz,	T _A = 25°c	-0.15		0.15		
	+	f = 3300 Hz		-0.35		0.05	15	
Receive filter gain, relative	to absolute+	f = 3400 Hz		-0.8		0	dB	
		f = 4000 Hz				-14		
Absolute [‡] receive gain var and supply voltage	iation with temperature	T _A = full range,	See Note 3	-0.1		0.1	dB	
		Sinusoidal test method:	$3 \text{ dBm0} \ge \text{input level}$ $\ge -40 \text{ dBm0}$			±0.2		
Receive gain tracking error	r with level	reference input PCM code corresponds to an ideally	-40 dBm0 > input level ≥ -50 dBm0			±0.4	dB	
		encoded – 10 dBm0 signal	−50 dBm0 > input level ≥ −55 dBm0			±0.8		
		Pseudo-noise test method:	3 dBm0 ≥ input level ≥ −40 dBm0			±0.25		
Transmit and receive gain level (A-law, CCITT G 712)	0	reference input PCM code corresponds to an ideally	-40 dBm0 > input level ≥ -50 dBm0			±0.3	dB	
		encoded – 10 dBm0 signal	-50 dBm0 > input level ≥ -55 dBm0			±0.45		

[†] All typical values are at V_{CC} = 5 V, V_{BB} = –5 V, and T_A = 25°C.

[‡] Absolute rms signal levels are defined as follows: $V_I = 1.2276 V = 0 \text{ dBm0} = 4 \text{ dBm}$ at f = 1.02 kHz with $R_L = 600 \Omega$. NOTE 3: Full range for the TP3056B is 0°C to 70°C.



operating characteristics, over operating free-air temperature range, V_{CC} = 5 V ±5%, V_{BB} = -5 V ±5%, GND at 0 V, V_I = 1.2276 V, f = 1.02 kHz, transmit input amplifier connected for unity gain, noninverting, in A-law and μ -law modes, (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS	MIN	гүр†	MAX	UNIT
Transmit delay, absolute (at 0 dBm0)	f = 1600 Hz		290	315	μs
	f = 500 Hz to 600 Hz		195	220	
Transmit delay, relative to absolute‡ Receive delay, absolute (at 0 dBm0)	f = 600 Hz to 800 Hz		120	145	
	f = 800 Hz to 1000 Hz		50	75	
	f = 1000 Hz to 1600 Hz		20	40	μs
	f = 1600 Hz to 2600 Hz		55	75	
	f = 2600 Hz to 2800 Hz		80	105	
	f = 2800 Hz to 3000 Hz		130	155	
Receive delay, absolute (at 0 dBm0)	f = 1600 Hz		180	200	μs
	f = 500 Hz to 1000 Hz	-40	-25		
	f = 1000 Hz to 1600 Hz	-30	-20		
Receive delay, relative to absolute [‡]	f = 1600 Hz to 2600 Hz		70	90	μs
	f = 2600 Hz to 2800 Hz		100	125	
	f = 2800 Hz to 3000 Hz		140	175	

envelope delay distortion with frequency

[†] All typical values are at V_{CC} = 5 V, V_{BB} = -5 V, and T_A = 25° C.

[‡] Absolute rms signal levels are defined as follows: $V_I = 1.2276$ V = 0 dBm0 = 4 dBm at f = 1.02 kHz with $R_L = 600 \Omega$.

noise

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Transmit noise, C-message weighted	μ-law	VFXI = 0 V		9	14	dBrnC0
Transmit noise, psophometric weighted (see Note 4)	A-law	VFXI = 0 V		-78	-75	dBm0p
Receive noise, C-message weighted	μ-law	PCM code equals alternating positive and negative zero.		2	4	dBrnC0
Receive noise, psophometric weighted	A-law	PCM code equals positive zero.		-86	-83	dBm0p
Noise, single frequency		VFXI+ = 0 V, $f = 0 kHz$ to 100 kHz, Loop-around measurement			-53	dBm0

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $V_{BB} = -5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Measured by extrapolation from the distortion test result. This parameter is achieved through use of patented circuitry and is not recommended for applications in which the composite signals on the transmit side are below –55 dBm0.

crosstalk

PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
Crosstalk, transmit to receive	f = 300 Hz to 3000 Hz,	DR at steady PCM code		-90	-75	dB
Crosstalk, receive to transmit (see Note 5)	VFXI = 0 V,	f = 300 Hz to 3000 Hz		-90	-75	dB

[†] All typical values are at V_{CC} = 5 V, V_{BB} = -5 V, and T_A = 25° C.

NOTE 5: Receive-to-transmit crosstalk is measured with a - 50 dBm0 activation signal applied at VFXI+.

power amplifiers

PARAMETER	TEST CONDITION	MIN	MAX	UNIT	
		$R_L = 600 \Omega$	1.65		
Maximum 0 dBm0 rms level for better than ± 0.1 dB linearity over the range if -10 dBm0 to 3 dBm0	Balanced load,R _L , connected between VFRO and Gnd	$R_L = 1200 \Omega$	1.75		V
		$R_L = 30 \text{ k}\Omega$	2		V _{rms}
Signal/distortion	R _L = 600 Ω	50		dB	



operating characteristics, over operating free-air temperature range, V_{CC} = 5 V ±5%, V_{BB} = -5 V ±5%, GND at 0 V, V_I = 1.2276 V, f = 1.02 kHz, transmit input amplifier connected for unity gain, noninverting, in A-law and μ -law modes, (unless otherwise noted) (continued)

power supply rejection

PARAMETER	TEST CON	TEST CONDITIONS			MAX	UNIT
Positive power-supply rejection, transmit	V _{CC} = 5 V + 100 mVrms, VFXI+ = -50 dBm0		A-law	38		dB
		f = 0 Hz to 4 kHz	μ-law	38		dBC†
		f = 4 kHz to 50 kHz		40		dB
Negative power-supply rejection, transmit	V _{BB} = -5 V + 100 mVrms, VFXI+ = -50 dBm0	f = 0 Hz to 4 kHz	A-law	35		dB
			μ-law	35		dBC†
		f = 4 kHz to 50 kHz		40		dB
Positive power-supply rejection, receive	PCM code equals positive zero, V _{CC} = 5 V + 100 mVrms	f = 0 Hz to 4 kHz	A-law	40		dB
			μ-law	40		dBC†
		f = 4 kHz to 50 kHz		40		dB
Negative power-supply rejection, receive	PCM code equals positive zero, $V_{BB} = -5 V + 100 mVrms$	f = 0 Hz to 4 kHz	A-law	38		dB
			μ-law	38		dBC†
	$ABB = -3.6 \pm 100$ moments	f = 4 kHz to 50 kHz		40		dB
0 dBm0, 300-Hz to 3400-Hz input applied to DR (measure individual image signals at VFRO)				-30	dB	
Spurious out-of-band signals at the channel output (VFRO)	f = 4600 Hz to 7600 Hz				-33	
	f = 7600 Hz to 8400 Hz				-40	dB
	f = 8400 Hz to 100 kHz				-40	

[†] The unit dBC applies to C-message weighting.



operating characteristics, over operating free-air temperature range, V_{CC} = 5 V ±5%, V_{BB} = -5 V ±5%, GND at 0 V, V_I = 1.2276 V, f = 1.02 kHz, transmit input amplifier connected for unity gain, noninverting, in A-law and μ -law modes, (unless otherwise noted) (continued)

distortion

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
	Level = 3 dBm0		33		
	Level = 0 dBm0 to - 30 dBm0		36		
		Transmit	29		dBC†
Signal-to-distortion ratio, transmit or receive half-channel [‡]		Receive	30		UBC I
		Transmit	14		
	Level = -55 dBm0	Receive	15		
Single-frequency distortion products, transmit				-46	dB
Single-frequency distortion products, receive				-46	dB
Intermodulation distortion	Loop-around measurement, VFXI+ = -4 dBm0 to -21 dBm0, Two frequencies in the range of 300 Hz to 3400 Hz			-41	dB
	Level = -3 dBm0		33		
	Level = $-6 \text{ dBm0 to} -27 \text{ dBm0}$	36		dB	
Signal-to-distortion ratio, transmit half-channel (A-law) (CCITT G.714)§	Level = -34 dBm0		33.5		
	Level = -40 dBm0		28.5		
	Level = -55 dBm0		13.5		
	Level = -3 dBm0		33		
	Level = $-6 \text{ dBm0 to} -27 \text{ dBm0}$		36		
Signal-to-distortion ratio, receive half-channel (A-law) (CCITT G.714)§	Level = -34 dBm0		34.2		dB
	Level = -40 dBm0		30		
	Level = -55 dBm0		15		

[†] The unit dBC applies to C-message weighting.

[‡] Sinusoidal test method (see Note 6)

§ Pseudo-noise test method

NOTE 6: µ-law measurements are made using a C-message weighted filter, and A-law measurements are made using a psophometric weighted filter.



timing requirements over recommended ranges of operating conditions (see Figures 1 and 2)

			MIN	NOM	MAX	UNIT
fclock(M)	Frequency of master clock	MCLK		2.048		MHz
fclock(B)	Frequency of bit clock, transmit	BCLK	64		2048	kHz
^t w1	Pulse duration, MCLK high		160			ns
t _{w2}	Pulse duration, MCLK low		160			ns
t _{r1}	Rise time of master clock (20% to 80%)	MCLK			50	ns
t _{f1}	Fall time of master clock (80% to 20%)				50	ns
t _{r2}	Rise time of bit clock (20% to 80%), transmit	BCLK			50	ns
^t f2	Fall time of bit clock (80% to 20%), transmit	DOLK			50	ns
^t su1	Setup time, BCLK high (and FSX in long-frame sync mode) before MCLK \downarrow (first bit clock after the leading edge of FSX)		100			ns
t _{w3}	Pulse duration, BCLK high, V _{IH} = 2.2 V		160			ns
t _{w4}	Pulse duration, BCLK low, $V_{IL} = 0.6 V$		160			ns
t _{h1}	Hold time, FSX or FSR low after BCLK low (long frame only)		0			ns
^t h2	Hold time, BCLK high after FSX or FSR \uparrow (short frame only)		0			ns
t _{su2}	Setup time, FSX or FSR high before BCLK \downarrow (long frame only)		80			ns
t _{su3}	Setup time, DR valid before BCLK \downarrow		50			ns
t _{h3}	Hold time, DR valid after BCLK \downarrow		50			ns
t _{su4}	Setup time, FSX or FSR high before BCLK \downarrow , short-frame sync pulse (1 or 2 bit-clock periods long) (see Note 7)		50			ns
^t h4	Hold time, FSX or FSR high after BCLK \downarrow , short-frame sync pulse (1 or 2 bit-clock periods long) (see Note 7)		100			ns
^t h5	Hold time, FSX or FSR high after BCLK \downarrow , long-frame sync pulse (from 3 to 8 bit-clock periods long)		100			ns
^t w5	Minimum pulse duration of FSX or FSR (frame sync pulse — low level), 64-kbps operating mode		160			ns

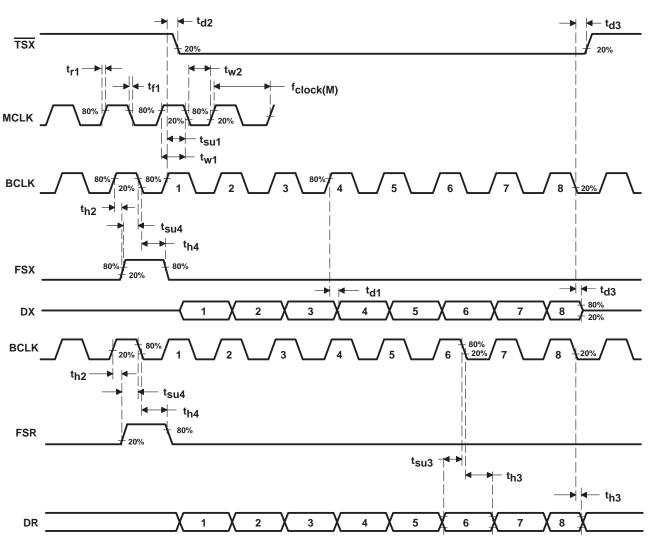
NOTE 7: For short-frame sync timing, FSR and FSX must go high while their respective bit clocks are high.

switching characteristics over recommended ranges of operating conditions (see Figures 1 and 2)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
^t d1	Delay time, BCLK high to data valid at DX	Load = 150 pF plus 2 LSTTL loads [†]	0	140	ns
t _{d2}	Delay time, BCLK high to TSX low	Load = 150 pF plus 2 LSTTL loads [†]		140	ns
t _{d3}	Delay time, BCLK (or 8 clock FSX in long frame only) low to data output (DX) disabled		50	165	ns
t _{d4}	Delay time, FSX or BCLK high to data valid at DX (long frame only)	C _L = 0 pF to 150 pF	20	165	ns

[†] Nominal input value for an LSTTL load is 18 k Ω .

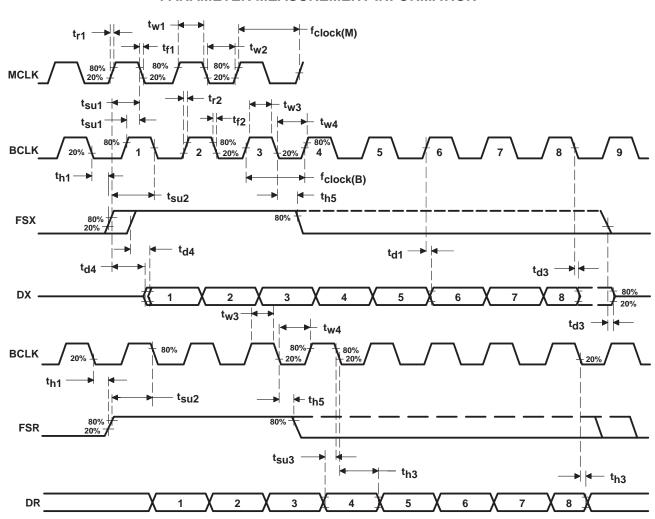




PARAMETER MEASUREMENT INFORMATION

Figure 1. Short Frame Sync Timing





PARAMETER MEASUREMENT INFORMATION

Figure 2. Long Frame Sync Timing



PRINCIPLES OF OPERATION

system reliability and design considerations

TP3056B system reliability and design considerations are described in the following paragraphs.

latch-up

Latch-up is possible in all CMOS devices. It is caused by the firing of a parasitic SCR that is present due to the inherent nature of CMOS. When a latch-up occurs, the device draws excessive amounts of current and will continue to draw heavy current until power is removed. Latch-up can result in permanent damage to the device if supply current to the device is not limited.

Even though the TP3056B is heavily protected against latch-up, it is still possible to cause latch-up under certain conditions in which excess current is forced into or out of one or more terminals. Latch-up can occur when the positive supply voltage drops momentarily below ground, when the negative supply voltage rises momentarily above ground, or possibly if a signal is applied to a terminal after power has been applied but before the ground is connected. This can happen if the device is hot-inserted into a card with the power applied, or if the device is mounted on a card that has an edge connector and the card is hot-inserted into a system with the power on.

To help ensure that latch-up does not occur, it is considered good design practice to connect a reverse-biased Schottky diode with a forward voltage drop of less than or equal to 0.4 V (1N5711 or equivalent) between the power supply and GND (see Figure 3). If it is possible that a TP3056B-equipped card that has an edge connector could be hot-inserted into a powered-up system, it is also important to ensure that the ground edge connector traces are longer than the power and signal traces so that the card ground is always the first to make contact.

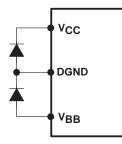


Figure 3. Latch-Up Protection Diode Connection



PRINCIPLES OF OPERATION

system reliability and design considerations (continued)

device power-up sequence

Latch-up also can occur if a signal source is connected without the device being properly grounded. A signal applied to one terminal could then find a ground through another signal terminal on the device. To ensure proper operation of the device and as a safeguard against this sort of latch-up, it is recommended that the following power-up sequence always be used:

- 1. Ensure that no signals are applied to the device before the power-up sequence is complete.
- 2. Connect GND.
- 3. Apply V_{BB} (most negative voltage).
- 4. Apply V_{CC} (most positive voltage).
- 5. Force a power down condition in the device.
- 6. Connect clocks.
- 7. Release the power down condition.
- 8. Apply FS synchronization pulses.
- 9. Apply the signal inputs.

When powering down the device, this procedure should be followed in the reverse order.

internal sequencing

Power-on reset circuitry initializes the TP3056B device when power is first applied, placing it in the power-down mode. The DX and VFRO outputs go into the high-impedance state and all nonessential circuitry is disabled. A low level applied to the PDN terminal powers up the device and activates all internal circuits. The 3-state PCM data output, DX, remains in the high-impedance state until the arrival of the second FSX pulse.

general operation

A 2.048-MHz clock signal applied to MCLK serves as the master clock for both the receive and the transmit directions. BCLK must have a bit clock signal applied to it, which then serves as the bit clock for both the receive and the transmit directions. BCLK can be in the range from 64 kHz to 2.048 MHz, but must be synchronous with MCLK.

The encoding cycle begins with each FSX pulse, and the PCM data from the previous cycle is shifted out of the enabled DX output on the rising edge of BCLK. After eight bit-clock periods, the 3-state DX output is returned to the high-impedance state. With an FSR pulse, PCM data is latched in via DR on the falling edge of BCLK. FSX and FSR must be synchronous with MCLK.



PRINCIPLES OF OPERATION

short-frame sync operation

long-frame sync operation

Both FSX and FSR must be three or more bit-clock periods long to use the long-frame sync mode with timing relationships as shown in Figure 2. Using the transmit frame sync (FSX), the device determines whether a shortor long-frame sync pulse is being used. For 64-kHz operation, the frame-sync pulse must be kept low for a minimum of 160 ns. The rising edge of FSX or BCLK, whichever occurs later, enables the 3-state output buffer, outputting the sign bit at DX. The next seven rising edges of BCLK shift out the remaining seven bits. The falling edge of BCLK following the eighth rising edge, or FSX going low, whichever occurs later, disables DX. A rising edge on FSR, the receive-frame sync pulse, causes the PCM data at DR to be latched in on the next eight falling edges of BCLK.

transmit section

The transmit section consists of an input amplifier, filters, and an encoding ADC. The input is an operational amplifier with provision for gain adjustment using two external resistors. The low-noise and wide-bandwidth characteristics of these devices provide gains in excess of 20 dB across the audio passband. The operational amplifier drives a unity-gain filter consisting of an RC active prefilter followed by an eighth-order switched-capacitor band-pass filter clocked at 256 kHz. The output of this filter is routed to the encoder sample-and-hold circuit. The ADC is a compressing type and converts the analog signal to PCM data in accordance with μ -law or A-law coding conventions, as selected. A precision voltage reference provides a nominal input overload voltage of 2.5 V peak.

The sampling of the filter output is controlled by the FSX frame-sync pulse; then the successive-approximation encoding cycle begins. The resulting 8-bit code is loaded into a buffer and shifted out through DX at the next FSX pulse. The total encoding delay is approximately 290 μ s. Any offset voltage due to the filters or comparator is cancelled by sign-bit integration.

receive section

The receive section is unity gain and consists of an expanding DAC, filters, and a power amplifier. Decoding is μ -law or A-law (as selected by the ASEL terminal), and the decoded analog output signal is routed to the input of a fifth-order switched-capacitor low-pass filter. This filter is clocked at 256 kHz and corrects for the (sin x)/x attenuation caused by the 8-kHz sample/hold of the DAC. Next is a second-order RC active post-filter/power amplifier capable of driving an external 600- Ω load.

When FSR goes high, the data at DR is stepped in on the falling edge of the next eight BCLK clocks. At the end of the decoder time slot, the decoding cycle begins and 10 μ s later, the decoder DAC output is updated. The decoder delay is about 10 μ s (decoder update) plus 110 μ s (filter delay) plus 62.5 μ s (1/2 frame), or a total of approximately 180 μ s.



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APPLICATION INFORMATION

power supplies

While the terminals of the TP3056B device is well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed-circuit board can be plugged into a hot socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the device ANLG GND terminal. This minimizes the interaction of ground return currents flowing through a common bus impedance. V_{CC} and V_{BB} supplies should be decoupled by connecting 0.1- μ F decoupling capacitors to this common point. These bypass capacitors must be connected as close as possible to the device V_{CC} and V_{BB} terminals.

For best performance, the ground point of each codec/filter on a card should be connected to a common card ground in star formation rather than via a ground bus. This common ground point should be decoupled to V_{CC} and V_{BB} with 10-µF capacitors.

Figure 4 shows a typical TP3056B application.

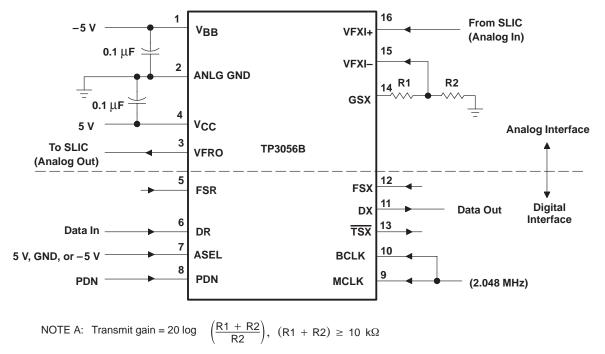


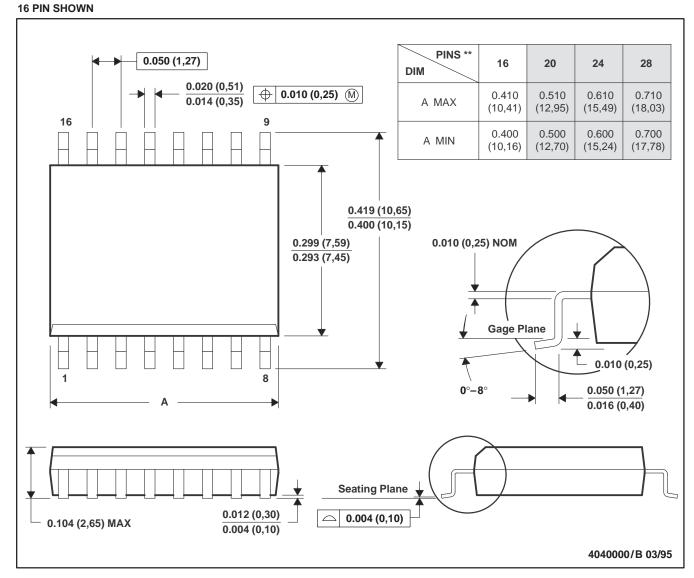
Figure 4. Typical Synchronous Application



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

DW (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

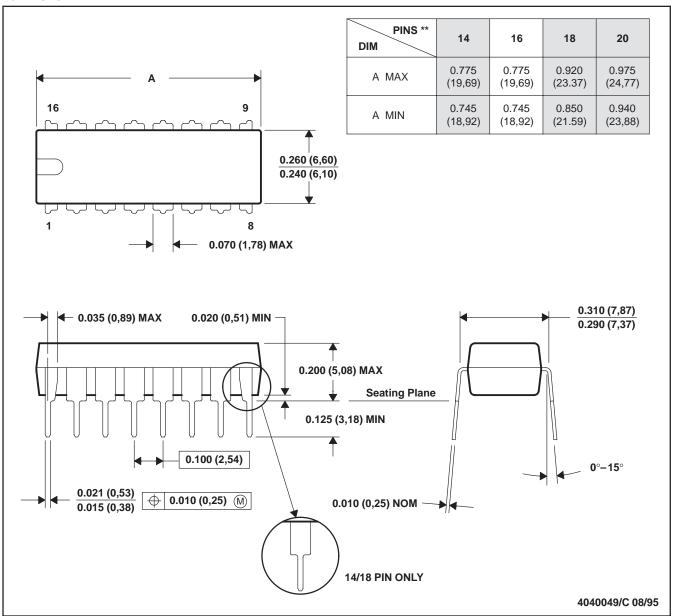


MECHANICAL DATA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE





NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 (20 pin package is shorter then MS-001.)



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